

Specification of Thermoelectric Module

TEFC1-01818P

Description

The 18 couples, 3.8 mm × 3.8/4.8mm size porch type module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 74 °C, designed for superior cooling and heating up to 100/200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

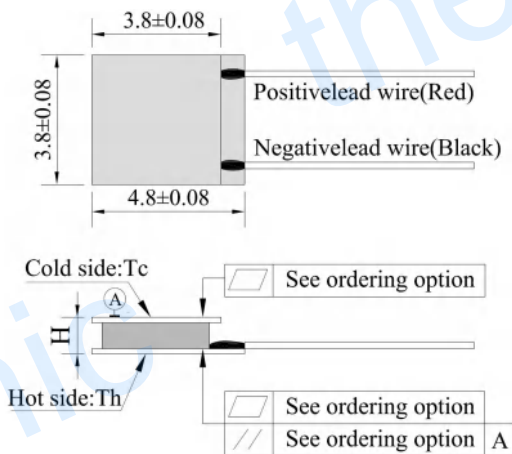
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	2.38	2.56	Voltage applied to the module at DT _{max}
I _{max} (amps)	1.8	1.8	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	2.72	2.97	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	1.0	1.1	The module resistance is tested under AC
Tolerance (%)	10%		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 1.1 ± 0.1	0: 0.03/0.03	20±3/Specify
TF	1: 1.1 ± 0.03	1: 0.015/0.015	20±3/Specify

Eg. TF01: Thickness 1.1 ± 0.1 (mm) and Flatness 0.015/0.015 (mm)

Manufacturing Options

A. Solder:

1. T100: BiSn (T_{melt}=138°C)
2. T200: CuAgSn (T_{melt} = 217°C)
3. T240: SbSn (T_{melt} = 240°C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

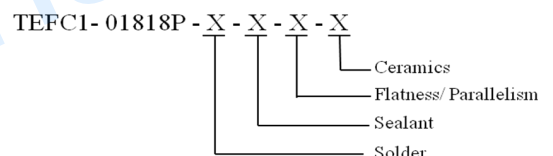
C. Ceramics:

1. Alumina (Al₂O₃, white 96%)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

Naming for the Module



TEFC1- 01818P- T100 -NS - TF01 - AIO

T100: Solder, BiSn (Melting Point=138 °C)

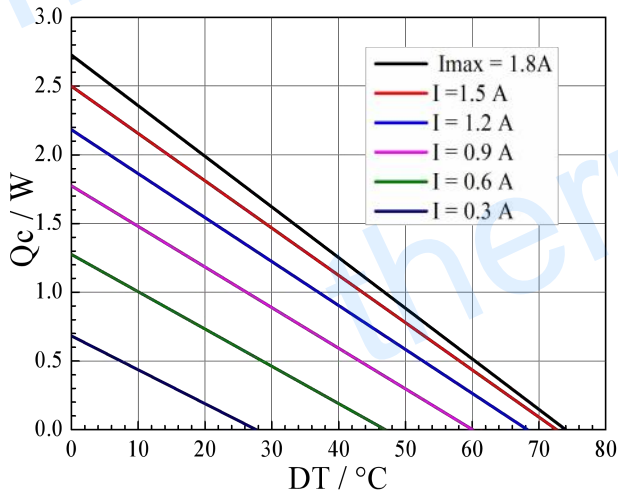
NS: No sealing

AIO: Alumina white 96%

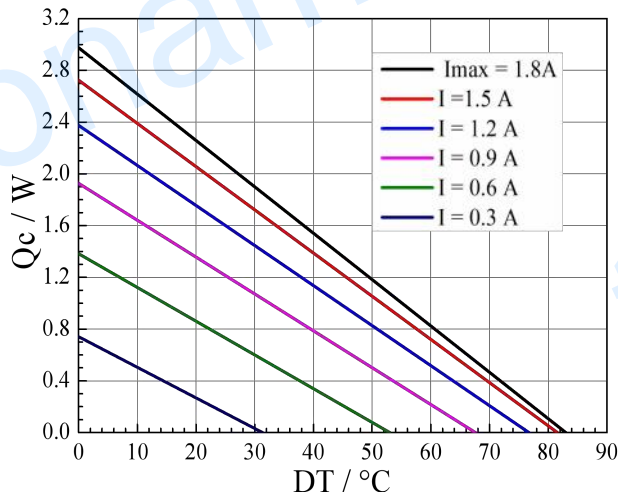
Specification of Thermoelectric Module

TEFC1-01818P

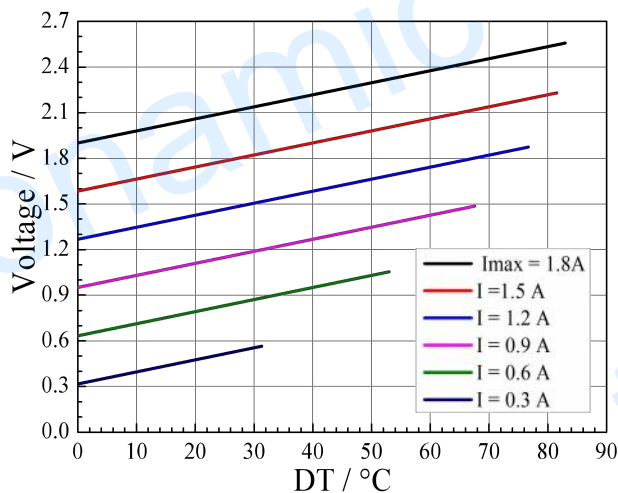
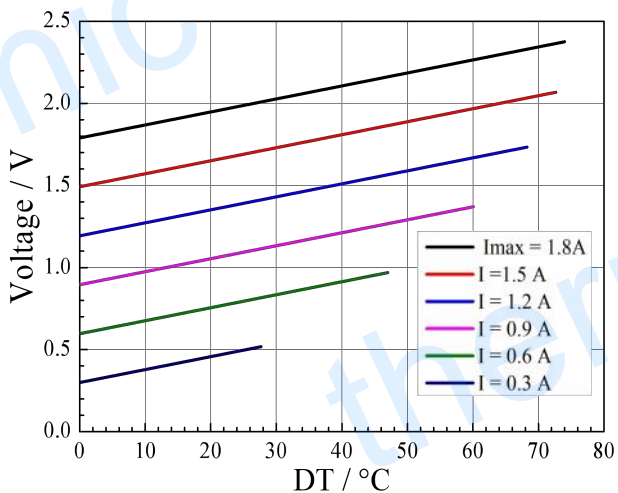
Performance Curves at Th=27 °C



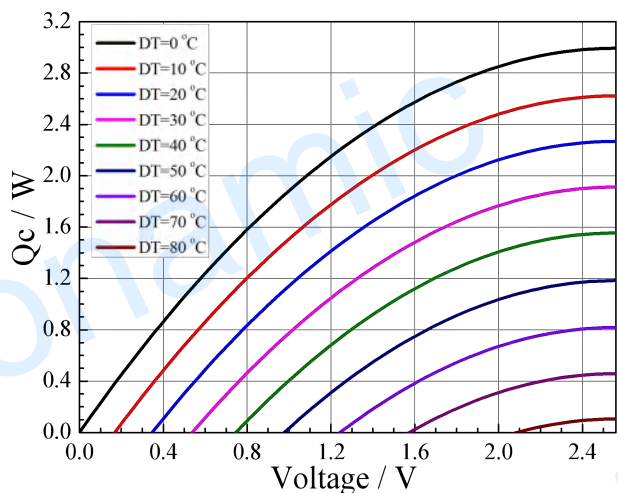
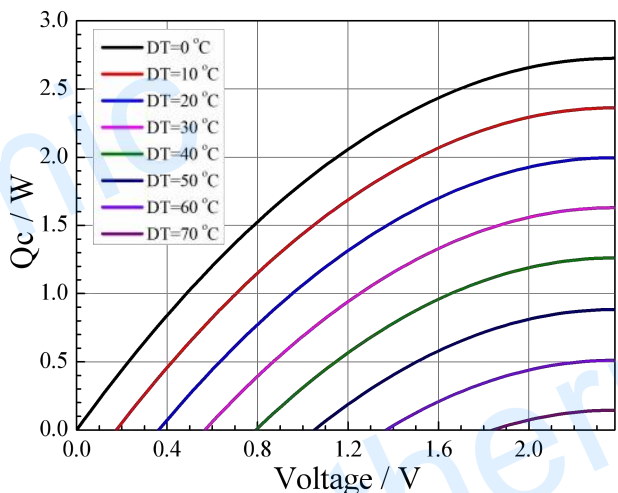
Performance Curves at Th=50 °C



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(DT)$

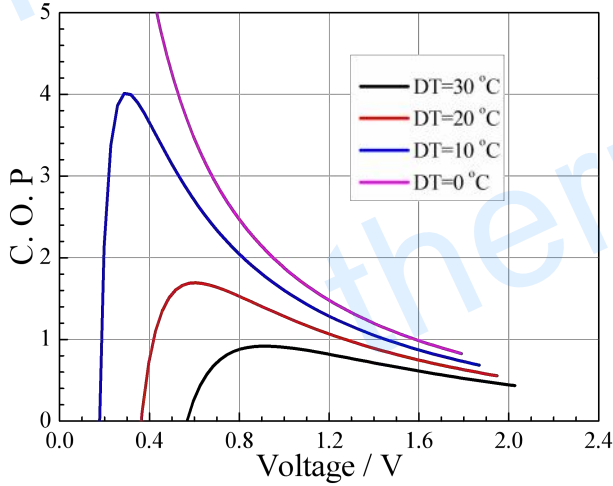


Standard Performance Graph $Q_c = f(V)$

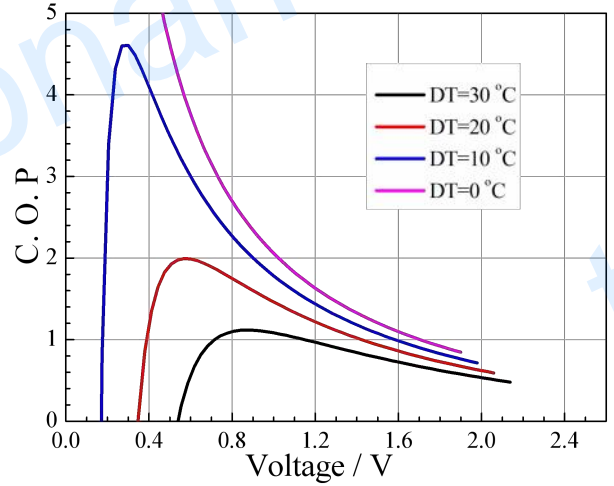
Specification of Thermoelectric Module

TEFC1-01818P

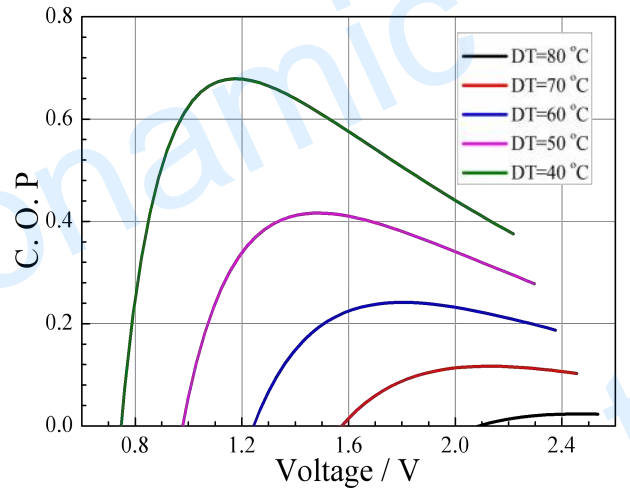
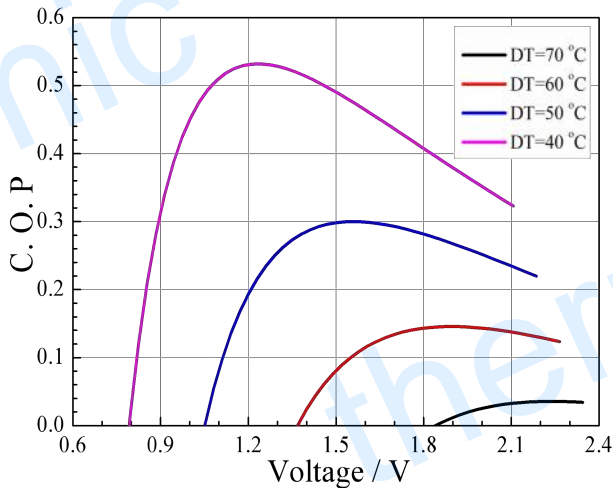
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 70/80 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.